

# **Product Termination Notification**

Product Group: SIL/Mon Nov 27, 2023/PTN-SIL-052-2023-REV-0



## Conversion to Copper (Cu) Wire - SQ3427EV

For further information, please contact your regional Vishay office.

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**Description of Change:** The affected part number listed in this notification will be converted to a Copper wire material set. The new ordering code is SQ3427CEV-T1\_GE3, which has the exact same product performance and fit as SQ3427EV. There will be no change to the wafer fab or assembly location (Note: parts with \_BE3 suffix will be consolidated to a single assembly location at Simconix). There will be no changes to the parameters on the datasheet (reference: SQ3427CEV Doc # 62369 Rev.B).

Reason for Change: Standardization of materials

Expected Influence on Quality/Reliability/Performance: None

Part Numbers/Series/Families Affected: SQ3427EV-T1\_GE3, SQ3427EV-T1\_BE3,

Vishay Brand(S): Vishay Siliconix

**CONTACT INFORMATION** 

Time Schedule:

Last Time Buy Date: Mon Jun 3, 2024 Last Time Ship Date: Tue Dec 3, 2024

Sample Availability: Qualified samples of replacement product are available on request

Product Identification: SQ3427CEV-T1\_GE3

Qualification Data: AEC Q101 qualification data of replacement product is available. Qualification PPAP is available now.

This PTN is considered approved, without further notification, unless we receive specific customer concerns before Mon Jun 3, 2024 or as specified by contract.

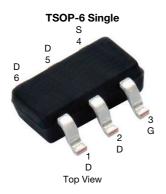
Issued By: Lance Gurrola, automostechsupport@vishay.com



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## Automotive P-Channel 60 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	-60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.095			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.135			
I <sub>D</sub> (A)	-5.3			
Configuration	Single			

Marking Code: 9Q

#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>g</sub> and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

(1, 2, 5, 6) D
(3) G
(4) S
P-Channel MOSFET

ORDERING INFORMATION					
Package	TSOP-6				
Lead (Pb)-free and halogen-free	SQ3427CEV (for detailed order number please see <a href="https://www.vishay.com/doc?79771">www.vishay.com/doc?79771</a> )				

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V <sub>DS</sub>	-60	V		
Gate-Source Voltage		$V_{GS}$	as ± 20			
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	-5.3			
	T <sub>C</sub> = 125 °C	l <sub>D</sub>	-3			
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	-6.3	Α		
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	-21			
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	-21			
Single Pulse Avalanche Energy	L = 0.1 IIIH	E <sub>AS</sub>	22	mJ		
Martin and Barras Direction for	T <sub>C</sub> = 25 °C	Б	5	W		
Maximum Power Dissipation	T <sub>C</sub> = 125 °C	$P_{D}$	1.6	VV		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>sta</sub>	-55 to +175	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount b	$R_{thJA}$	110	°C/W		
Junction-to-Foot (Drain)		$R_{thJF}$	30	G/ <b>VV</b>		

#### Notes

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. When mounted on 1" square PCB (FR4 material).



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = -250 \mu A$		-60	-	-	V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$		-2	-2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>GS</sub> = 0 V V <sub>DS</sub> = -60 V		-	-	-1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -60 V, T <sub>J</sub> = 125 °C	-	-	-50	μΑ	
		$V_{GS} = 0 V$	V <sub>DS</sub> = -60 V, T <sub>J</sub> = 175 °C	-	-	-150	1	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = -10 V	$V_{DS} \le -5 \text{ V}$	-10	-	-	Α	
		V <sub>GS</sub> = -10 V	I <sub>D</sub> = -4.5 A	-	0.079	0.095		
Dunin Course On Otata Basistana 8		V <sub>GS</sub> = -10 V	I <sub>D</sub> = -4.5 A, T <sub>J</sub> = 125 °C	-	-	0.148	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -4.5 A, T <sub>J</sub> = 175 °C	-	-	0.178		
		V <sub>GS</sub> = -4.5 V	$I_D = -3.5 \text{ A}$	-	0.112	0.135		
Forward Transconductancea	9 <sub>fs</sub>	V <sub>DS</sub> = -15 V, I <sub>D</sub> = -4 A		-	9	-	S	
Dynamic <sup>b</sup>								
Input Capacitance	C <sub>iss</sub>		V <sub>DS</sub> = -30 V, f = 1 MHz	-	726	1000	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	91	120		
Reverse Transfer Capacitance	C <sub>rss</sub>			-	56	80		
Total Gate Charge c	$Q_g$				16.9	22	nC	
Gate-Source Charge c	$Q_{gs}$	$V_{GS} = -10 \text{ V}$ $V_{DS} = -30 \text{ V}, I_{D} = -5 \text{ A}$		-	2.9	-		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			-	4.1	-	1	
Gate Resistance	R <sub>g</sub>		f = 1 MHz		5	7.5	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		$V_{DD} = -30 \text{ V, R}_1 = 6 \Omega$		8	12	- ns	
Rise Time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> :			24	35		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong -5 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		-	25	38		
Fall Time <sup>c</sup>	t <sub>f</sub>		1		33	50		
Source-Drain Diode Ratings and Characte	ristics <sup>b</sup>							
Pulsed Current <sup>a</sup>	I <sub>SM</sub>				-	-21	Α	
Forward Voltage	$V_{SD}$	I <sub>F</sub> =	I <sub>F</sub> = -1.6 A, V <sub>GS</sub> = 0 V		-0.8	-1.2	V	
Body diode reverse recovery time	t <sub>rr</sub>			-	23	46	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>	]	1 A di/d+ 100 A /:	-	27	54	nC	
Reverse recovery fall time	ta	] I <sub>F</sub> = -1./	A, di/dt = 100 A/μs	-	20	-		
Reverse recovery rise time	t <sub>b</sub>	7	1		3	-	ns	
Body diode peak reverse recovery current	I <sub>RM(REC)</sub>			-	-2.86	-	Α	

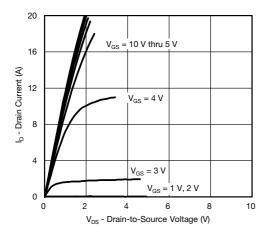
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

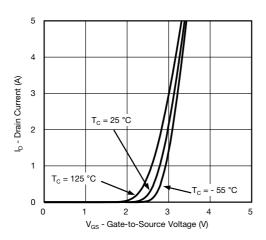
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



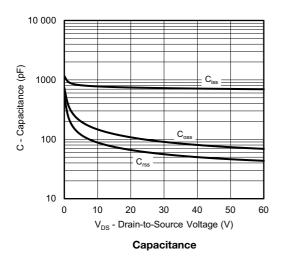
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

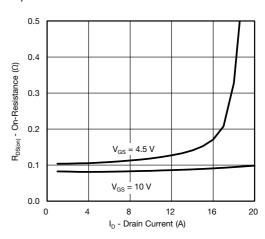


#### **Output Characteristics**

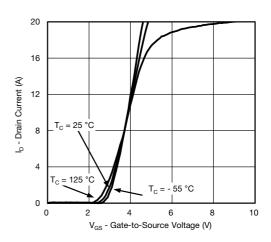


**Transfer Characteristics** 

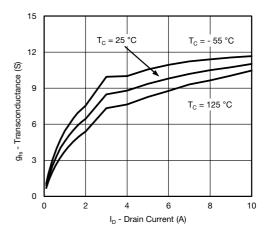




On-Resistance vs. Drain Current and Gate Voltage



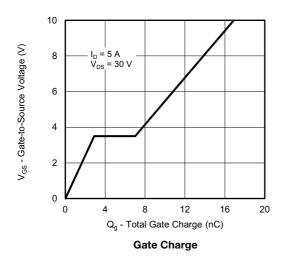
Transfer Characteristics

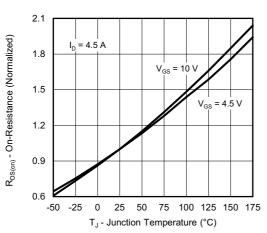


Transconductance

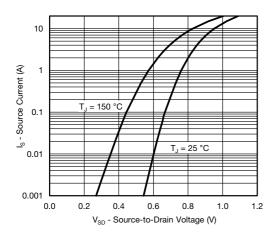
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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

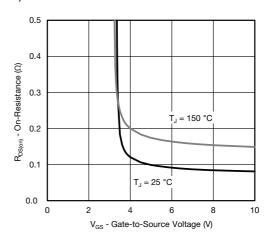




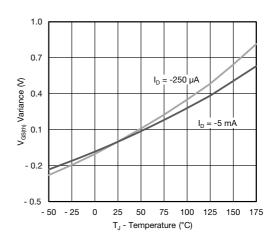
On-Resistance vs. Junction Temperature



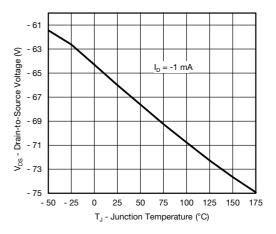
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



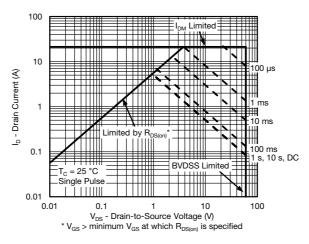
Threshold Voltage



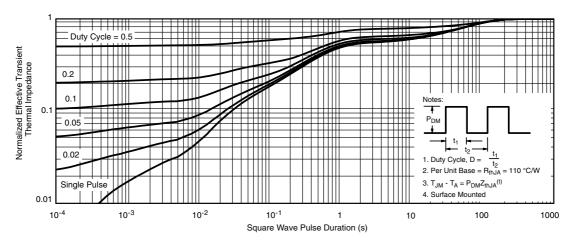
**Drain-to-Source Voltage vs. Junction Temperature** 

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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



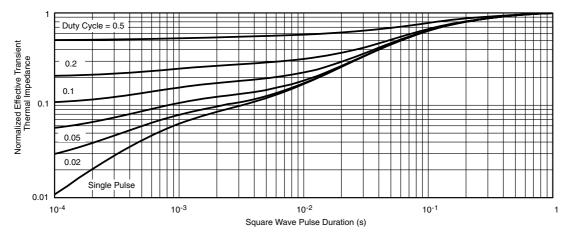
Safe Operating Area, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg262369">www.vishay.com/ppg262369</a>.



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